5% duty cycle to keep load from overheating 30-40 Hz

Kikisui lugs are 30mm wide and reach 10mm beyond hole centers

With output lugs on right side of board and for board to be top side up then:

Ground lug needs to be toward upper edge of board & Vout lug 55mm further down

5/28/2014
slew = 5mV/us, 1.52VID max, individual phase interleave when in 4 phases
no turbo mode, no phase shedding, zero loadline

Preliminary
You should delete the nylon screws/standoffs and/or the bumpers as needed for your design (or substitute other parts from Hardware.IntLib). Bumpers are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.
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